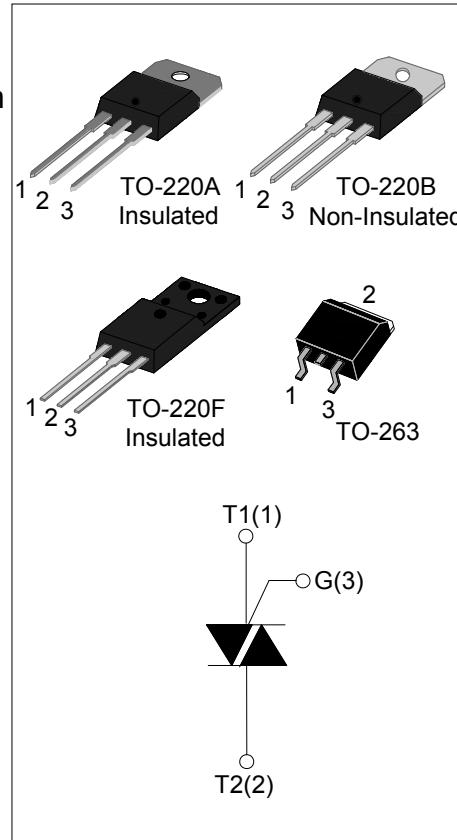


DESCRIPTION:

With high ability to withstand the shock loading of large current, YR BTA/BTB20 series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.

From all three terminals to external heatsink, YR BTA/BTB20 provides a rated insulation voltage of 2500 Vrms, complying with UL standards .



MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	20	A
V_{DRM}/V_{RRM}	600 and 800 and 1200	V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T_{stg}	-40-150	°C
Operating junction temperature range	T_j	-40-125	°C
Repetitive peak off-state voltage ($T_j=25^\circ\text{C}$)	V_{DRM}	600/800/1200	V
Repetitive peak reverse voltage ($T_j=25^\circ\text{C}$)	V_{RRM}	600/800/1200	V
Non repetitive surge peak Off-state voltage	V_{DSM}	$V_{DRM} + 100$	V
Non repetitive peak reverse voltage	V_{RSM}	$V_{RRM} + 100$	V
RMS on-state current	$I_{T(RMS)}$	20	A
	TO-220A(Ins) ($T_c=75^\circ\text{C}$)		
	TO-220B(Non-Ins) ($T_c=90^\circ\text{C}$)		
	TO-220F(Ins) ($T_c=75^\circ\text{C}$)		
	TO-263 ($T_c=65^\circ\text{C}$)		

BTA/BTB20 TRIACs

Non repetitive surge peak on-state current (full cycle, F=50Hz)	I _{TSM}	200	A
I ² t value for fusing (tp=10ms)	I ² t	200	A ² s
Critical rate of rise of on-state current (I _G =2×I _{GT})	dI/dt	100	A/μs
Peak gate current	I _{GM}	4	A
Average gate power dissipation	P _{G(AV)}	1	W
Peak gate power	P _{GM}	10	W

ELECTRICAL CHARACTERISTICS (T_j=25°C unless otherwise specified)

3 Quadrants

Symbol	Test Condition	Quadrant	Value		Unit
			BW	CW	
I _{GT}	V _D =12V R _L =33Ω	I - II -III	MAX	50	35 mA
V _{GT}		I - II -III	MAX	1.3	V
V _{GD}	V _D =V _{DRM} T _j =125°C R _L =3.3KΩ	I - II -III	MIN	0.2	V
I _L	I _G =1.2I _{GT}	I -III	MAX	70	60 mA
		II		90	70
I _H	I _T =100mA	MAX	60	50	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125°C	MIN	1000	500	V/μs

4 Quadrants

Symbol	Test Condition	Quadrant		Value	Unit
I _{GT}	V _D =12V R _L =33Ω	I - II -III	MAX	50	mA
		IV		70	
V _{GT}	ALL	MAX		1.3	V
V _{GD}	V _D =V _{DRM} T _j =125°C R _L =3.3KΩ	ALL	MIN	0.2	V
I _L	I _G =1.2I _{GT}	I -III-IV	MAX	70	mA
		II		90	
I _H	I _T =100mA	MAX		60	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125°C	MIN		500	V/μs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V_{TM}	$I_{TM} = 28A$	$t_p = 380\mu s$	$T_j = 25^\circ C$	1.5 V
I_{DRM}	$V_D = V_{DRM}$	$V_R = V_{RRM}$	$T_j = 25^\circ C$	5 μA
I_{RRM}			$T_j = 125^\circ C$	2.5 mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-220A(Ins)	2.9
		TO-220B(Non-Ins)	1.9
		TO-220F(Ins)	2.1
		TO-263	2.9

BTA/BTB20 TRIACs

FIG.1 Maximum power dissipation versus RMS on-state current

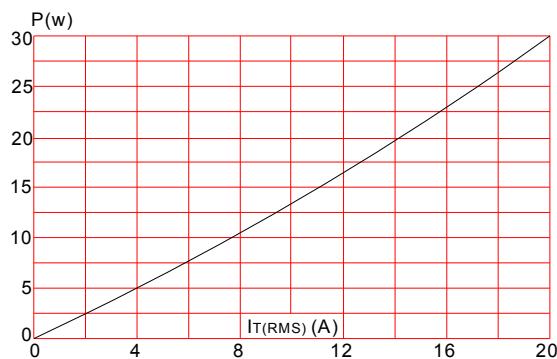


FIG.3: Surge peak on-state current versus number of cycles

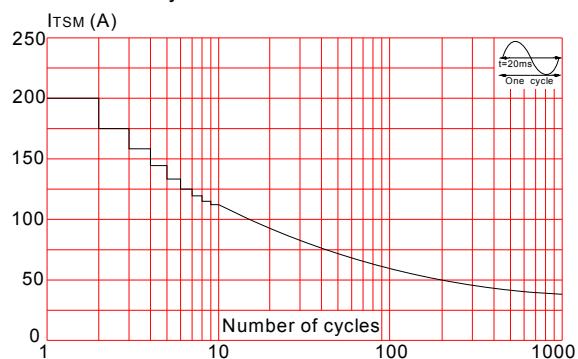


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I^2t ($dI/dt < 100\text{A}/\mu\text{s}$)

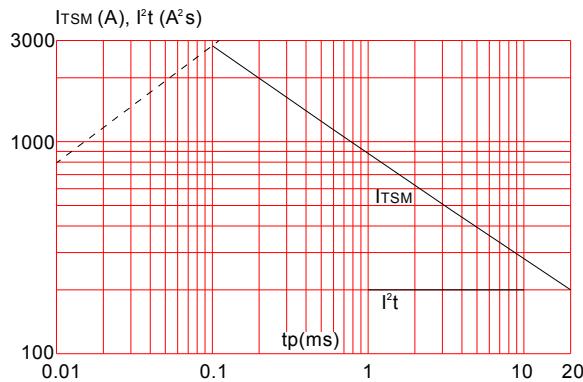


FIG.2: RMS on-state current versus case temperature

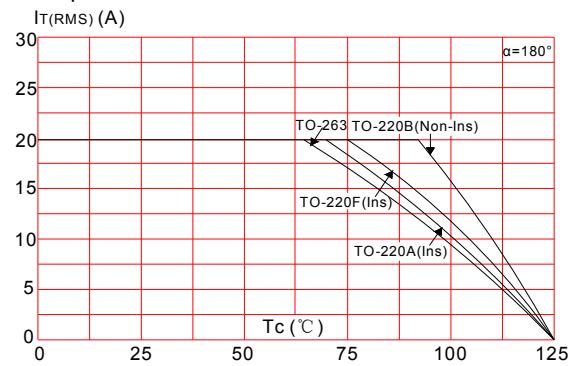


FIG.4: On-state characteristics (maximum values)

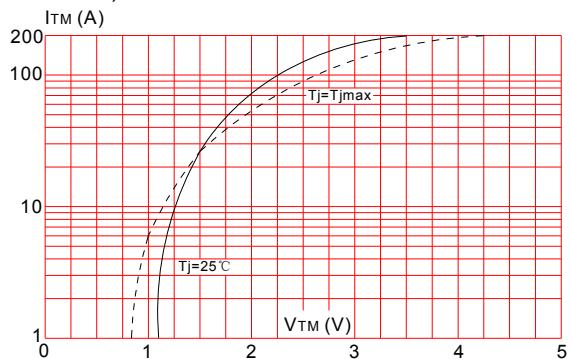


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

